



Material Content Data Sheet



Halogen-Free

Sales Product Name ISC3XXN10NM6

Issued

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MA# MA005403060

Package PG-TDSON-8-37

Weight*

113.94 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.318	0.28	0.28	2790	2790
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		129	
	non noble metal	iron	7439-89-6	0.049	0.04		429	
	non noble metal	copper	7440-50-8	48.769	42.81	42.86	428045	428603
wire	noble metal	gold	7440-57-5	0.046	0.04	0.04	408	408
encapsulation	organic material	carbon black	1333-86-4	0.085	0.07		747	
	plastics	epoxy resin	-	6.720	5.90		58982	
	inorganic material	silicondioxide	60676-86-0	35.727	31.36	37.33	313577	373306
leadfinish	non noble metal	tin	7440-31-5	1.392	1.22	1.22	12213	12213
plating	noble metal	silver	7440-22-4	0.194	0.17	0.17	1701	1701
solder	non noble metal	tin	7440-31-5	0.010	0.01		86	
	noble metal	silver	7440-22-4	0.012	0.01		108	
	non noble metal	lead	7439-92-1	0.469	0.41	0.43	4115	4309
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.02		151	
	non noble metal	copper	7440-50-8	17.131	15.04	15.06	150361	150557
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			8	
	non noble metal	iron	7439-89-6	0.003			26	
	non noble metal	copper	7440-50-8	2.971	2.61	2.61	26079	26113
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

- Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
- Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
- All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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